



Integrated Device Technology

The Analog and Digital Company™


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**9P960AFLF**
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**Customer Support / Technical Support****DESCRIPTION**

PC BUFFER

**Recommended Application::** Dual DDR zero delay buffer**Product Description/Features:**

High performance, low jitter zero delay buffer  
 I2C for functional and output control  
 Dual bank 1-6 differential clock distribution  
 2 separate feedback in & out for input to output synchronization for each bank  
 Supports up to 4 DDR DIMMs  
 Supports up to DDRII - 1066MHz  
 Supports up to DDRIII (1.8V core) - 1333MHz

**Generic Part:**[9P960](#)**Category:**[DDR Solutions](#)**PARAMETERS**

|                                 |            |
|---------------------------------|------------|
| Temperature                     | C          |
| Voltage                         | 1.8 V      |
| Package                         | SSOP<br>48 |
| Speed                           | NA         |
| Output Style                    |            |
| Core Supply Voltage<br>(VDD)    |            |
| No. of Outputs                  |            |
| Min. Output Frequency           |            |
| Min. Input Frequency            |            |
| Output Supply Voltage<br>(VDDO) |            |
| No. of Inputs                   |            |
| Input Style                     |            |
| Max. Output Frequency           |            |
| Max. Input Frequency            |            |
| Temp. Grade                     |            |
| Multiplication/Divide<br>Value  |            |
| CPU Manufacturer                |            |
| Chipset                         |            |
| Yellow Cover Spec.              |            |
| Embedded                        |            |
| Suggested - Pkg. Voltage        |            |
| Temp. Range                     |            |

**PACKAGE**

|                                        |                       |
|----------------------------------------|-----------------------|
| Package                                | SSOP 48 (PVG48)       |
| Description                            | SSOP 300 MIL          |
| Status                                 | Active                |
| Class                                  | PLASTIC               |
| Category                               | <a href="#">Green</a> |
| Pb (Lead)<br>Free                      | <a href="#">Yes</a>   |
| Pb Free<br>Category                    | <a href="#">e3 Sn</a> |
| Mark                                   | F                     |
| Package<br>Type                        | SSOP                  |
| Lead Count                             | 48                    |
| Length                                 | 15.9 mm               |
| Width                                  | 7.5 mm                |
| Thickness                              | 2.3 mm                |
| Pitch                                  | 0.64 mm               |
| Tube / Tray                            | TUBE                  |
| Quantity per<br>Tube/Tray              | 30                    |
| Quantity per<br>Reel                   | 1000                  |
| Moisture<br>Sensitivity<br>Level (MSL) | 1                     |
| Moisture                               | Unlimited@<30C/85%    |

Exposure RH  
Floor Life  
Peak Reflow Temperature 260°C  
Rebake Conditions NA  
Related Package Documents [view documents](#)

#### DOCUMENTS

| Type                  | Title                                                         | Size   | Revision Date |
|-----------------------|---------------------------------------------------------------|--------|---------------|
| Misc                  | PC Clocks Contact Info                                        | 61 KB  | 05/29/2007    |
| Product Change Notice | PCN# : TB1010-01 Remove Country of Origin from Package Bottom | 677 KB | 11/21/2010    |
|                       | PCN# : A0807-02R1 Copper Bond Wire for SSOP, SOIC and TSSOP   | 144 KB | 01/06/2009    |
|                       | PCN# : A0807-02 Copper Bond Wire for SSOP, SOIC and TSSOP     | 144 KB | 07/30/2008    |
| Product Delete Notice | PDN# : M-07-01 SELECTED DIMM PRODUCT DISCONTINUANCE NOTICE    | 144 KB | 07/24/2007    |

#### DISTRIBUTOR INVENTORY

| Part | Distributor | Qty | Date | RFQ | Order |
|------|-------------|-----|------|-----|-------|
|------|-------------|-----|------|-----|-------|

No matches found.

#### CONTACTS

##### Sales Offices

► [Sales Offices and authorized distributors](#)

##### Technical Support

Clock Help

► WWW: [Clock Help](#)